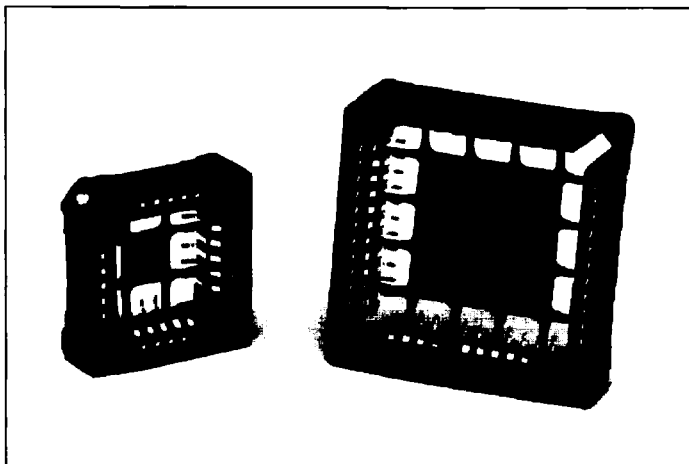


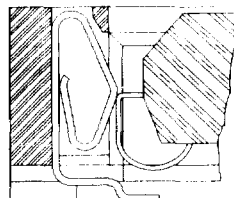
PLASTIC LEADED CHIP CARRIER SOCKETS PLCC-SMT Series



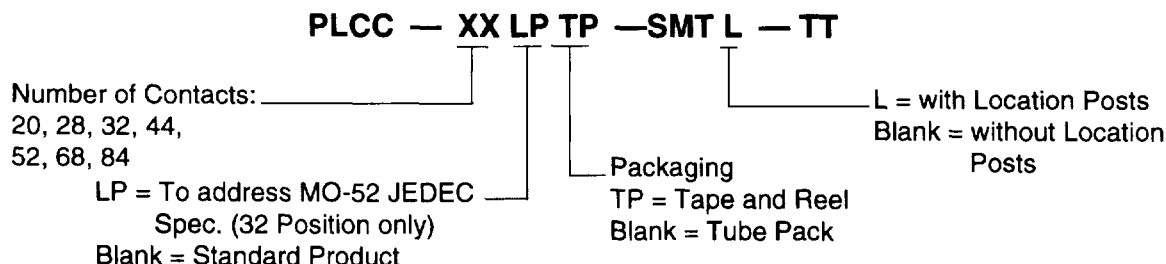
- Low profile; .200" maximum height
- Designed for automatic assembly
- Socket footprint same as device
- Open frame allows visual inspection of solder joints
- High temp insulator compatible with IR reflow and wave soldering
- Optional standoff on 32 position only to accommodate low profile MO-52 JEDEC Specifications
- Options: Tape and reel packaging
Location posts

Full Bellows Contact

The Robinson Nugent full bellows contact design offers higher spring properties which exert 200 grams of normal force per IC lead. This allows for a highly reliable contact interface and high retention of the PLCC device in the socket.



How to Order PLCC-SMT Series



Materials:

Body: High temp, black thermoplastic
Contacts: Phosphor Bronze

Environmental Specifications:

Temperature Rating: -55°C to +105°C
Vibrations per MIL: STD 1344, Method 3002
Humidity per MIL: STD 1344, Method 1002

Performance Characteristics:

Insertion Force: 180 g/pin maximum
Withdrawal Force: 28.35 g/pin minimum
Contact Resistance: 20 mΩ
Capacitance: 1 picofarad
Insulation Resistance: 1000 M ohms minimum
Dielectric Withstanding Voltage: 650 Volts AC
Current Rating: One Ampere
Flammability: UL 94V-0

Plating:

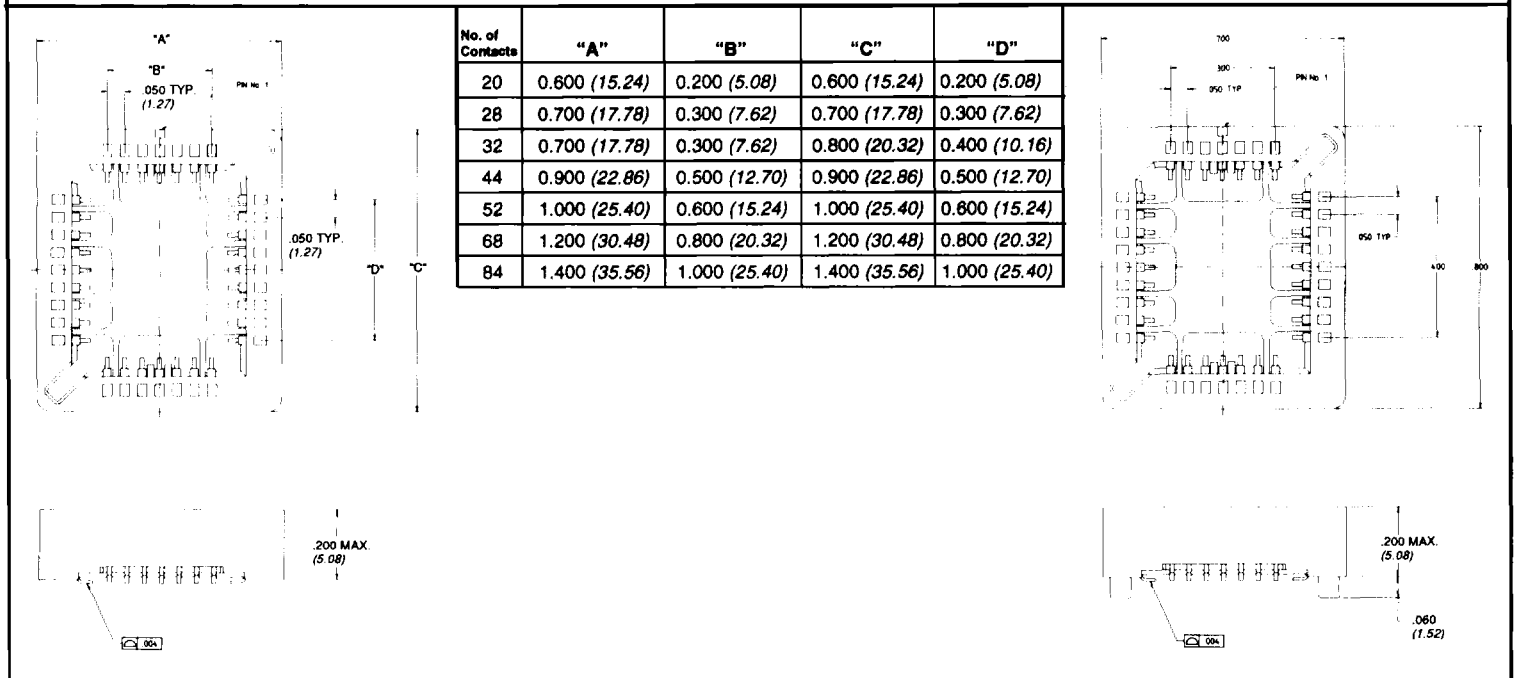
100 μinch (2.54 μm) minimum Tin
50 μinch (1.27 μm) minimum Nickel
underplate

HIGH DENSITY/SMT

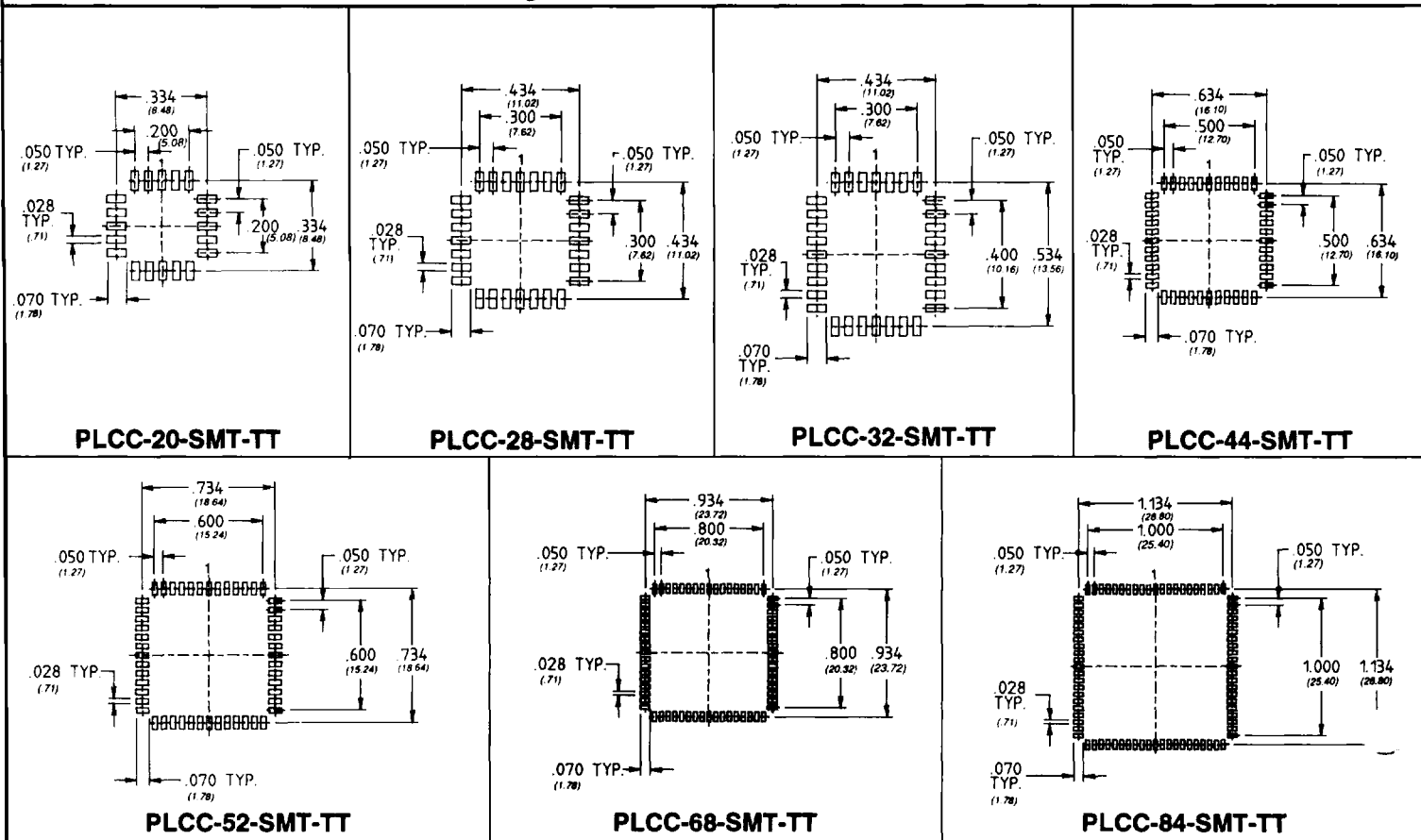


PLCC-XX-SMT-TT Without Location Post

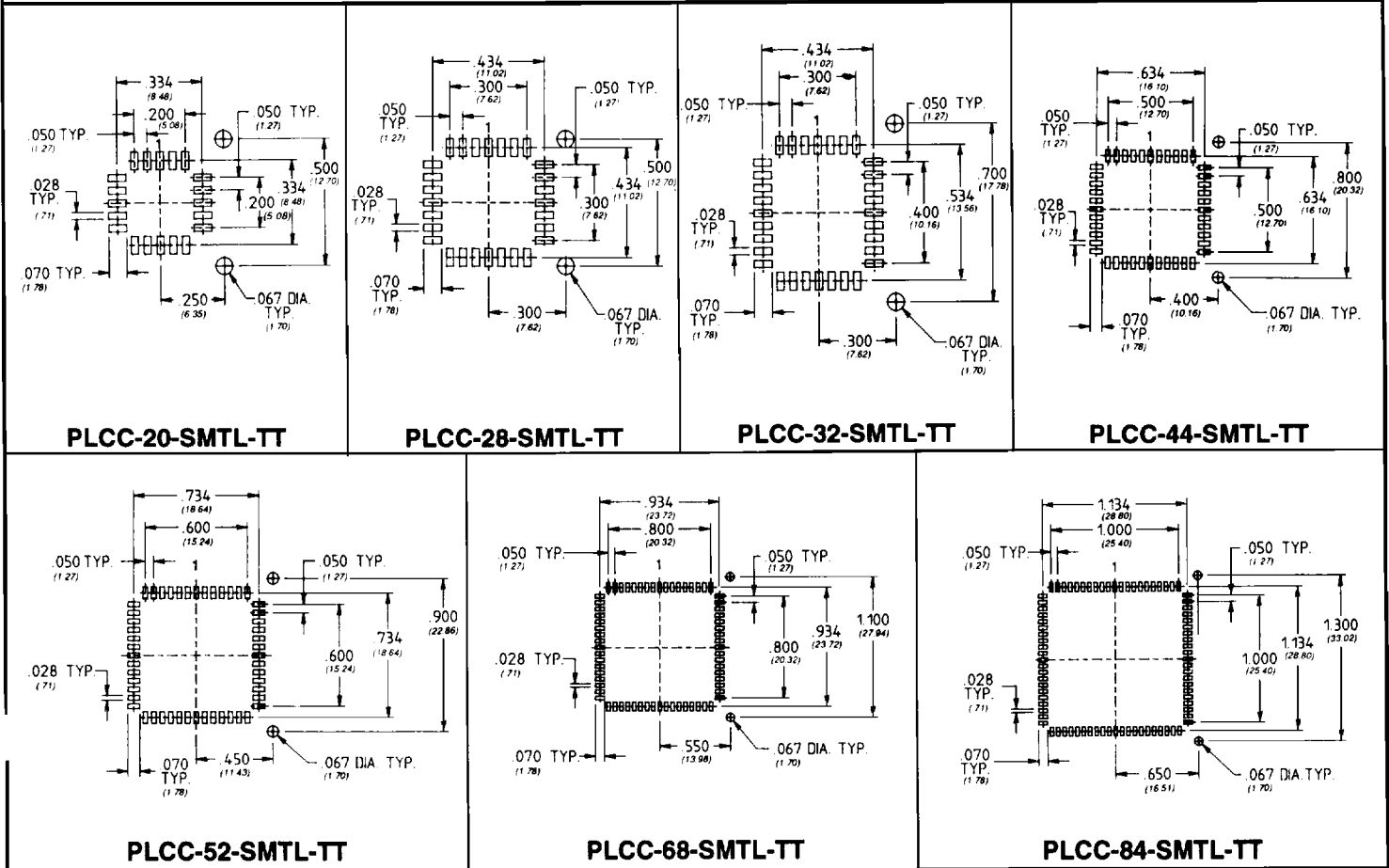
PLCC-XX-SMTL-TT With Location Post



PLCC-XX-SMT-TT Recommended Mounting Pattern



PLCC-XX-SMTL-TT Recommended Mounting Pattern



HIGH DENSITY/SMT



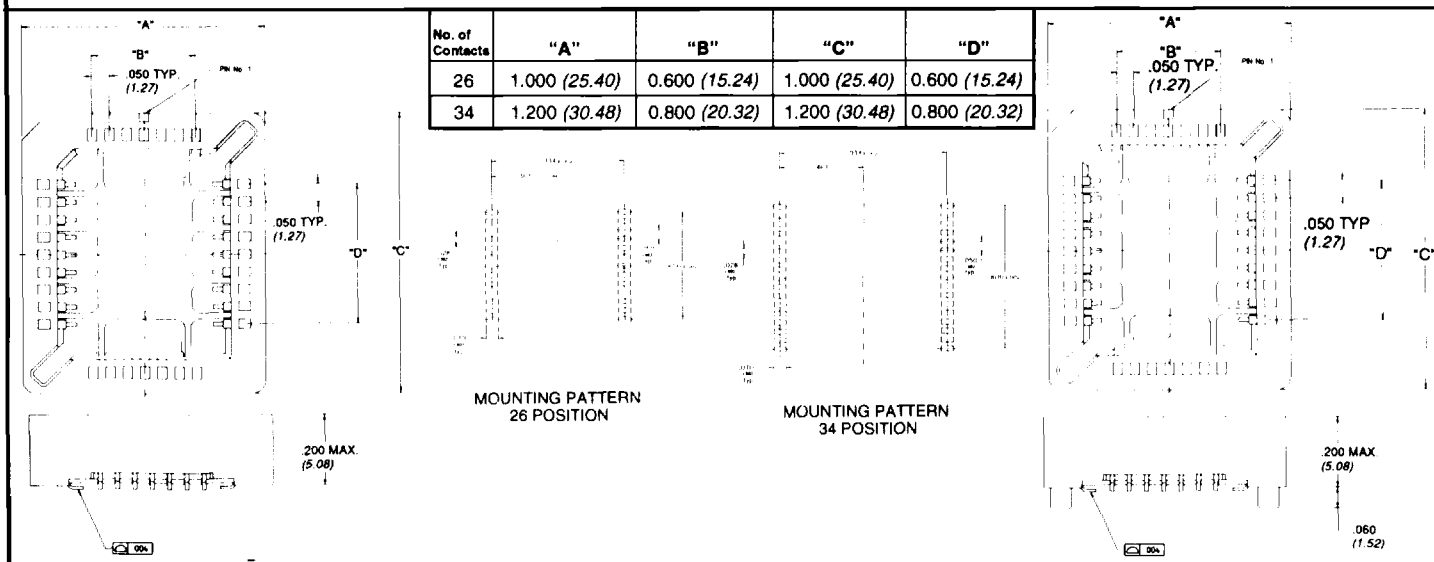
PLASTIC LEADED CHIP CARRIER SOCKETS

RTC/NVRAM Series



- SMT socket designed for 26 and 34 position real time clocks and nonvolatile static RAMs
- .004" coplanarity insures excellent solderability during IR processing eliminating potential rework
- Full bellows contact design provides reliable contact interface and high retention of device in socket
- Options: Tape and reel packaging
Location posts

PLCC-XX-SMT-TT
 Without Location Post

PLCC-XX-SMTL-TT
 With Location Post


How to Order

RTC/NVRAM Series

PLCC — 26 TP — SMT L - TT

Number of Contacts: 26, 34

Packaging: TP = Tape and Reel, Blank = Tube Pack

Plating: L = with Location Posts, Blank = without Location Posts

Materials:

Body: High temp thermoplastic
Contacts: Phosphor Bronze

Environmental Specifications:

Temperature Rating: -55°C to +105°C
Vibrations per MIL: STD 1344, Method 3002
Humidity per MIL: STD 1344, Method 1002

Performance Characteristics:

Insertion Force: 180 g/pin maximum
Withdrawal Force: 28.35 g/pin minimum
Contact Resistance: 20 mΩ
Capacitance: 1 picofarad
Insulation Resistance: 1000 M ohms minimum
Dielectric Withstanding Voltage: 650 Volts AC
Current Rating: One Ampere
Flammability: UL 94V-0

Plating:

100 μinch (2.54 μm) minimum TinLead
 50 μinch (1.27 μm) minimum Nickel underplate